

Method of Resin-Seal-Molding Electronic Component and Apparatus Therefor

ABSTRACT OF THE DISCLOSURE

A mold (110) for resin-seal-molding an electronic component is constituted by a first mold (111) and a second mold (112). A molding face (PL) of the molds has a substrate supply-set surface (113), which has a flat shape without a step. A pot block (140) is joined with and separated from a side position (110a) of the mold (110) perpendicular to the mold face (PL). In a state where the mold face and the pot block (140) are joined, a molten resin material in the pot block (140) is injected into a cavity (114). Further, a mold-opening is performed where the second mold (112) is separated away from the one mold (111) in a state where the resin-seal-molded substrate is fixed to a mold surface of the one mold (111). According to the present method, the overall structure of the mold (110) for resin-seal-molding an electronic component can be simplified.

Fig 21